# **ESD Protection Diode**

**Micro-Packaged Diodes for ESD Protection** 

## **ESD9C3.3ST5G SERIES**

The ESD9C3.3ST5G Series is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications.

### **Specification Features:**

- Low Capacitance 6.2 pF 13 pF
- Low Clamping Voltage
- Small Body Outline Dimensions: 0.039" x 0.024" (1.0 mm x 0.60 mm)
- Low Body Height: 0.016" (0.40 mm) Max
- Stand-off Voltage: 3.3 V, 5 V
- Low Leakage
- Response Time < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These are Pb–Free Devices

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Contact Air		±8.0 ±15	kV
Total Power Dissipation on FR–5 Board (Note 1) @ $T_A = 25^{\circ}C$	P <sub>D</sub>	150	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.  $1 - ER 5 = 1.0 \times 0.75 \times 0.62$  in

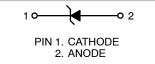
1. FR-5 = 1.0 x 0.75 x 0.62 in.

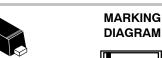
See Application Note AND8308/D for further description of survivability specs.



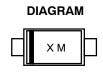
### **ON Semiconductor®**

### www.onsemi.com









X = Specific Device Code M = Date Code

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
ESD9CxxST5G	SOD-923 (Pb-Free)	8000/Tape & Reel
SZESD9CxxST5G	SOD-923 (Pb-Free)	8000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **DEVICE MARKING INFORMATION**

See specific marking information in the device marking column of the table on page 2 of this data sheet.

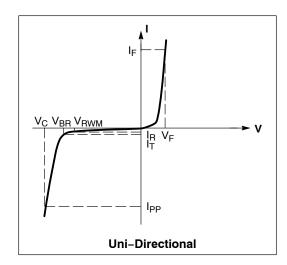
### ESD9C3.3ST5G SERIES

### **ELECTRICAL CHARACTERISTICS**

 $(T_{\Delta} = 25^{\circ}C \text{ unless otherwise noted})$ 

Symbol	Parameter				
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current				
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>				
V <sub>RWM</sub>	Working Peak Reverse Voltage				
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>				
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>				
Ι <sub>Τ</sub>	Test Current				
I <sub>F</sub>	Forward Current				
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>				
P <sub>pk</sub>	Peak Power Dissipation				
С	Max. Capacitance $@V_R = 0$ and f = 1 MHz				

\*See Application Note AND8308/D for detailed explanations of datasheet parameters.

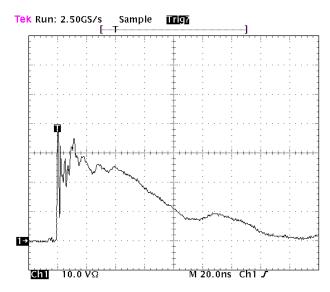


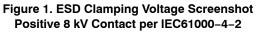
**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted, V<sub>F</sub> = 1.1 V Max. @ I<sub>F</sub> = 10 mA)

	Device	V <sub>RWM</sub> (V)	I <sub>R</sub> (μΑ) @ V <sub>RWM</sub>	V <sub>BR</sub> (V) @ I <sub>T</sub> (Note 2)	ΙŢ	<b>C (pF)</b> (Note 3)	<b>C (pF)</b> (Note 3)	Vc	
Device	Marking	Мах	Мах	Min	mA	Тур	Max	Per IEC61000-4-2 (Note 4)	
ESD9C3.3ST5G	R	3.3	1.0	5.0	1.0	12.8	13	Figures 1 and 2 See Below	
ESD9C5.0ST5G	Р	5.0	0.5	11.0	1.0	6.0	6.2	(Note 5)	

2. V<sub>BR</sub> is measured with a pulse test current I<sub>T</sub> at an ambient temperature of 25°C. 3. Capacitance at f = 1 MHz, V<sub>R</sub> = 0 V, T<sub>A</sub> = 25°C. 4. For test procedure see Figures 3 and 4 and Application Note AND8307/D.

5. ESD9C5.0ST5G shown below. Other voltages available upon request.





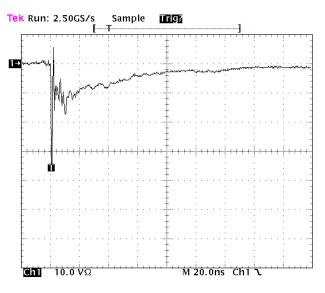
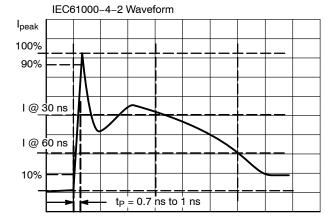


Figure 2. ESD Clamping Voltage Screenshot Negative 8 kV Contact per IEC61000-4-2

## ESD9C3.3ST5G SERIES

### IEC 61000-4-2 Spec.

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8





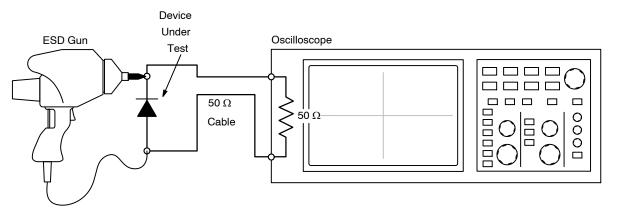


Figure 4. Diagram of ESD Test Setup

### The following is taken from Application Note AND8308/D – Interpretation of Datasheet Parameters for ESD Devices.

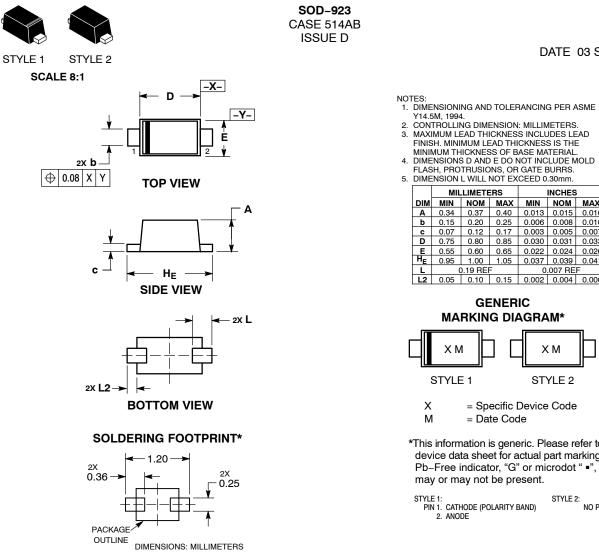
### **ESD Voltage Clamping**

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000–4–2 waveform. Since the IEC61000–4–2 was written as a pass/fail spec for larger

systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

## **MECHANICAL CASE OUTLINE**

PACKAGE DIMENSIONS



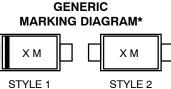
See Application Note AND8455/D for more mounting details

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



DATE 03 SEP 2020

	MIL	LIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.34	0.37	0.40	0.013	0.015	0.016	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.07	0.12	0.17	0.003	0.005	0.007	
D	0.75	0.80	0.85	0.030	0.031	0.033	
E	0.55	0.60	0.65	0.022	0.024	0.026	
HE	0.95	1.00	1.05	0.037	0.039	0.041	
L	0.19 REF			0.007 REF			
L2	0.05	0.10	0.15	0.002	0.004	0.006	



= Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ",

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